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- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages

description

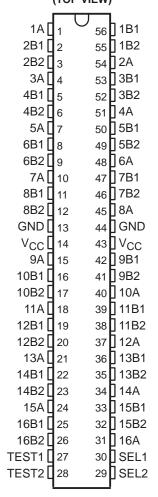
The SN74CBT16233 is a 16-bit 1-of-2 FET multiplexer/demultiplexer used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single path. This device can be used for memory interleaving, where two different banks of memory need to be addressed simultaneously. The device can be used as two 8-bit to 16-bit multiplexers or as one 16-bit to 32-bit multiplexer.

Two select (SEL1 and SEL2) inputs control the data flow. When the TEST inputs are asserted, the A port is connected to both the B1 and the B2 ports. SEL1, SEL2, and the TEST inputs can be driven with a 5-V CMOS, a 5-V TTL, or a low-voltage TTL driver.

This device is designed so it does not have through current when switching directions.

The SN74CBT16233 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



FUNCTION TABLE (each multiplexer/demultiplexer)

INPUTS		EUNCTION			
SEL	TEST	FUNCTION			
L	L	A = B1			
Н	L	A = B2			
Х	Н	A = B1 and A = B2			

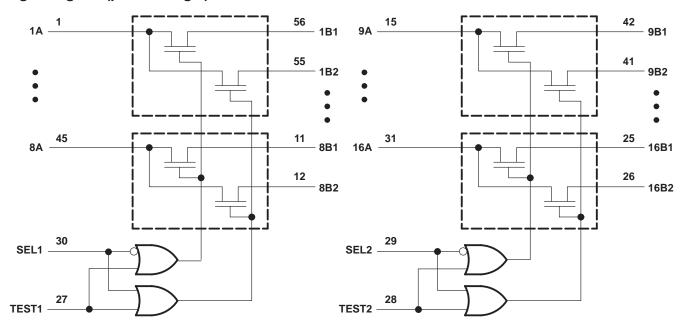


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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		0.5 V to V _{CC} + 0.5 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DGG package	64°C/W
-	DGV package	48°C/W
	DL package	56°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.75	5.25	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	0	70	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
VIK		$V_{CC} = 4.75 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2	V
Ц		$V_{CC} = 0$,	V _I = 5.25 V				10	μΑ
		V _{CC} = 5.25 V,	V _I = 5.25 V or GND				±1	μΑ
Icc		$V_{CC} = 5.25 \text{ V},$	I _O = 0,	$V_I = V_{CC}$ or GND			3	μΑ
Δl _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
Ci	Control inputs	$V_I = 3 V \text{ or } 0$				4.5		pF
C _{io(OFF)}		$V_O = 3 \text{ V or } 0$				4		pF
r _{on} §		V _{CC} = 4.75 V	V ₁ = 0	I _I = 64 mA		5	7	
				I _I = 30 mA		5	7	Ω
			V _I = 2.4 V,	I _I = 15 mA		7	12	

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} ¶	A or B	B or A		0.25	ns
^t pd	SEL	А	1.6	5.3	ns
^t en	TEST or SEL	В	1.3	5.2	ns
^t dis	TEST or SEL	В	1	5.3	ns

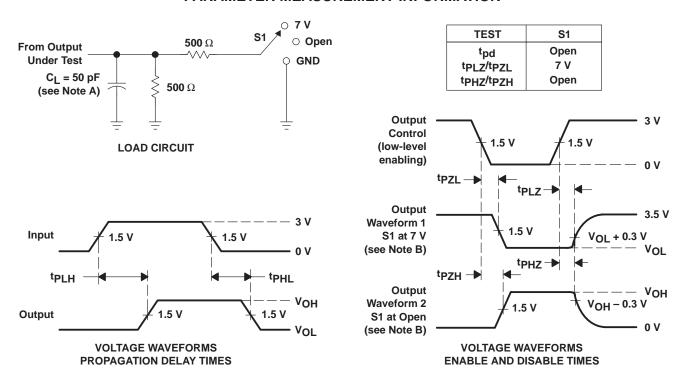
The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpZL and tpZH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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